MICROWAVE POWER GaAs FET

Internally Matched Power GaAs FETs (X, Ku-Band)

Features

- High power
 - $P_{1dB} = 33.5 \text{ dBm}$ at 9.5 GHz to 10.5 GHz
- High gain
- G_{1dB} = 7.5 dB at 9.5 GHz to 10.5 GHz
 Broadband internally matched
- Hermetically sealed package

RF Performance Specifications (T_a = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max.
Output Power at 1dB Compression Point	P _{1dB}	V _{DS} = 9V f = 9.5 - 10.5 GHz	dBm	32.5	33.5	-
Power Gain at 1dB Compression Point	G _{1dB}		dB	6.5	7.5	-
Drain Current	I _{DS}		А	-	0.85	1.1
Power Added Efficiency	η_{add}		%	-	24	-
Channel-Temperature Rise	ΔT_{ch}	$V_{DS} \times I_{DS} \times R_{th (c-c)}$	°C	-	-	60

Electrical Characteristics (T_a = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max.
Transconductance	gm	V _{DS} = 3V I _{DS} = 1.0A	mS	-	600	-
Pinch-off Voltage	V _{GSoff}	V _{DS} = 3V I _{DS} = 30 mA	V	-2	-3.5	-5
Saturated Drain Current	I _{DSS}	V _{DS} = 3V V _{GS} = 0V	Α	-	2.0	2.6
Gate-Source Breakdown Voltage	V _{GSO}	I _{GS} = -30 μA	V	-5	-	-
Thermal Resistance	R _{th (c-c)}	Channel to Case	°C/W	-	5	6

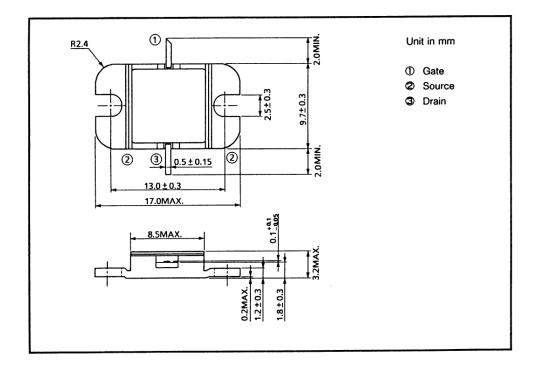
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Absolute Maximum Ratings (T_a = 25°C)

Characteristic	Symbol	Unit	Rating
Drain-Source Voltage	V _{DS}	V	15
Gate-Source Voltage	V _{GS}	V	-5
Drain Current	I _D	Α	2.6
Total Power Dissipation ($T_c = 25^{\circ}C$)	PT	W	15
Channel Temperature	T _{ch}	°C	175
Storage Temperature	T _{stg}	°C	-65 ~ 175

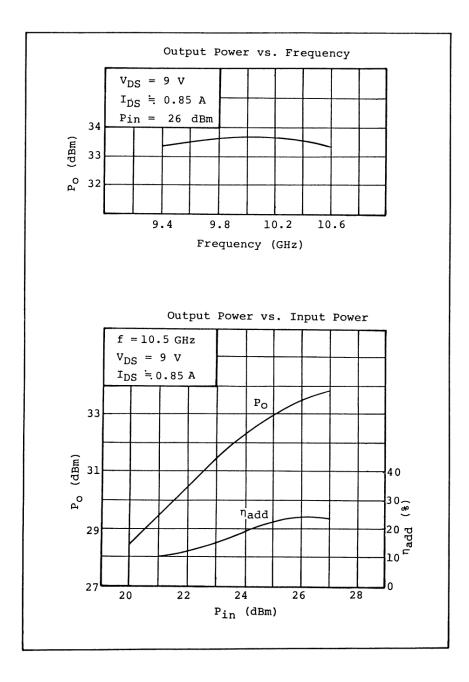
Package Outline (2-9D1B)



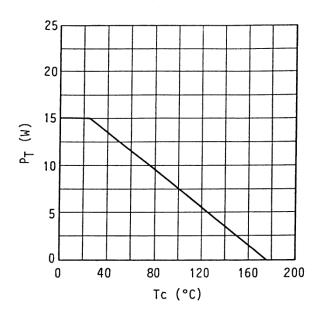
Handling Precautions for Packaged Type

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

RF Performances



Power Dissipation vs. Case Temperature



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V_{DS}=9V, I_{DS}=0.85A

